



BES2710IUC

Brief Datasheet

Ultra-low Power Bluetooth Audio Platform for TWS Applications with ANC

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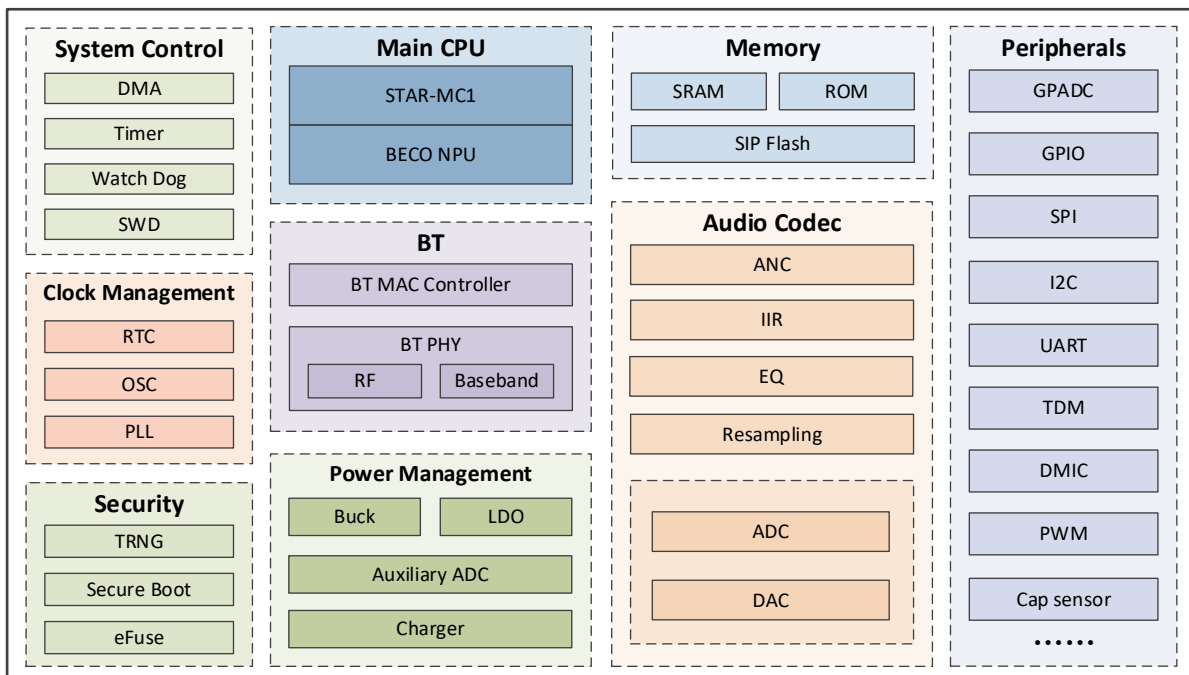
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1 General Description

The BES2710IUC is an ultra-low power Bluetooth audio SoC. The platform incorporates a CPU subsystem comprising a STAR-MC1 processor with a BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces. This combination minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem and a Power Management Unit (PMU) with an integrated charger. The highly integrated design is optimized through the use of IBRT technology, a BES patented sniffing technique that incorporates Forward Error Correction (FEC) for enhanced RF performance in TWS systems.



System Block Diagram

1.1 Applications

- TWS earbuds with ANC
- Other portable audio devices

1.2 Features & Specifications*

| | |
|------------------------|---|
| CPU Subsystem | STAR-MC1 |
| Memory and Storage | Shared 256 KB SRAM |
| | Flash in package |
| | boot ROM |
| Bluetooth Subsystem | Dual-mode BT 5.4 |
| Audio & Voice Features | 1x DAC |
| | 2x MICs |
| Peripheral Interfaces | GPADC/GPIO/SPI/I2C/UART/TDM/DMIC/PWM..... |
| Package | 36-L QFN |

* The content in the table is subject to change without notice.